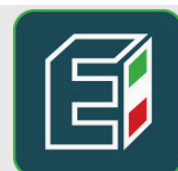


art. no.	page	R_{th} [K/W]	dissipation loss [W]	way of fixation	socket	suitable for processor type
ICK PGA 6 x 6 x 14	B 13	20	6.4	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 8 x 8 x 12	B 13	14.8	8.1	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 9 x 9	B 13	14	3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 11 x 11 x 8	B 13	16	7.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 11 x 11	B 13	10.9	4.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 11 x 11 x 12	B 14	12.3	3.9	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 14 x 14	B 14	10	4.9	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 14 x 14 x 10	B 14	10.5	11.2	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 14 x 14 x 14	B 14	9.6	12.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 14 x 14 x 12	B 14	9.8	5.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 15 x 15	B 15	9.4	5.9	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 16 x 16 x 8	B 15	14	4.9	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 16 x 16 x 10	B 15	10.5	12.9	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 16 x 16 x 12	B 15	9.3	6.2	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 17 x 17	B 15	8.6	6.9	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 17 x 17 x 8	B 16	13.2	5.2	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 17 x 17 x 12	B 16	9	6.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 18 x 18	B 16	8.4	7.2	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 19 x 19	B 16	8.6	7.6	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 19 x 19 x 12	B 16	9	6.9	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 20 x 20 x 10	B 17	8.5	15.1	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 20 x 20 x 8	B 17	12	6.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 20 x 20	B 17	7.6	8.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 20 x 20 K	B 17	7.6	8.3	fixing clamp	socket 7/ socket 370	IDT W2A/ AMD® K6-III/ AMD® K6-2/ MMX/ IDT C6/ Intel® Pentium®
ICK PGA 20 x 20 x 12	B 17	8	8.1	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 21 x 21	B 18	7	8.6	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 22 x 22	B 18	6.2	8.9	therm. conductive foil/ therm. cond. adhesive	universal	universal

Heatsinks for IC processor

art. no.	page	R_{th} [K/W]	dissipation loss [W]	way of fixation	socket	suitable for processor type
ICK PGA 25 x 25	B 18	5	11.1	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 10 x 10	B 19	32	1.8	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 10 x 10 x 10	B 19	28.5	1.9	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 11 x 11 x 6	B 19	31	1.9	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 11 x 11 x 10	B 19	27.5	2.2	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 11 x 11 x 14	B 20	25.5	2.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 12 x 12 x 18	B 20	24.5	2.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 14 x 14	B 20	30	2.1	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 14 x 14 x 10	B 20	27.4	2.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 14 x 14 x 14	B 20	25.9	2.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 15 x 15 x 6	B 21	29.5	2	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 15 x 15 x 10	B 21	27	2.2	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 15 x 15 x 14	B 21	25.5	2.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 19 x 19 x 6	B 21	27	2	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 19 x 19 x 10	B 21	26	2.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 19 x 19 x 14	B 21	21	2.8	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 21 x 21	B 22	24.3	2.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 21 x 21 x 10	B 22	23	2.6	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 21 x 21 x 14	B 22	20	3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 23 x 23	B 22	22.5	2.8	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 23 x 23 x 10	B 22	21.5	2.9	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 25 x 25 x 6	B 22	21.25	2.8	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 25 x 25 x 10	B 23	20	3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 25 x 25 x 14	B 23	17	3.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 27 x 27	B 23	20	3.1	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 27 x 27 x 10	B 23	18.5	3.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 27 x 27 x 14	B 23	13.5	9.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 27 x 27 x 22	B 24	10.5	9.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 29 x 29 x 6	B 24	19.5	3	therm. conductive foil/ therm. cond. adhesive	universal	universal



art. no.	page	R_{th} [K/W]	dissipation loss [W]	way of fixation	socket	suitable for processor type
ICK BGA 29 x 29 x 10	B 24	18	3.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 29 x 29 x 14	B 24	17	3.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 31 x 31	B 24	18.6	3.4	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 31 x 31 x 10	B 25	17	3.7	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 33 x 33 x 6	B 25	17.5	3.4	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 33 x 33 x 10	B 25	16.5	3.6	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 33 x 33 x 14	B 25	15	4	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 35 x 35	B 25	16.5	3.7	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 35 x 35 x 10	B 26	15.7	3.8	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 37 x 37 x 6	B 26	15.7	9.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 37 x 37 x 10	B 26	14	10.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 40 x 40	B 26	14.6	4.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 40 x 40 x 10	B 26	13.8	4.4	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 42,5 x 45	B 27	13.6	4.2	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 10 x 10 x 6,5	B 28	25	2.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 10 x 10 x 10	B 28	23.75	2.6	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 10 x 10 x 12,5	B 28	22.5	2.8	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 10 x 10 x 18,5	B 29	21.75	3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 14 x 14 x 6,5	B 29	9	5	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 14 x 14 x 10	B 29	8.8	5.1	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 14 x 14 x 12,5	B 29	8.1	5.4	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 14 x 14 x 18,5	B 29	7.9	5.6	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 17 x 17 x 15	B 30	8.36	5.95	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 17 x 17 x 20	B 30	7.89	6.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 18 x 18 x 6,5	B 30	7	7.7	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 18 x 18 x 10	B 30	6.8	8	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 22 x 22 x 6,5	B 30	6.4	13.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 22 x 22 x 10	B 31	5.9	8.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 22 x 22 x 18,5	B 31	5	10	therm. conductive foil/ therm. cond. adhesive	universal	universal

Heatsinks for IC processor

art. no.	page	R_{th} [K/W]	dissipation loss [W]	way of fixation	socket	suitable for processor type
ICK S 25 x 25 x 6,5	B 31	5.8	12.9	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 25 x 25 x 12,5	B 31	5.3	14.1	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 25 x 25 x 18,5	B 31	5.2	14.4	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 29 x 29 x 10	B 32	5.7	13.1	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 29 x 29 x 20	B 32	3.7	20.2	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 29 x 29 x 30	B 32	2.9	21	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 32 x 32 x 10	B 32	5.4	13.8	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 32 x 32 x 20	B 32	3.7	20.4	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 36 x 36 x 10	B 33	4.7	16	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 36 x 36 x 15	B 33	3.9	19.2	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 36 x 36 x 20	B 33	3.2	22	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 36 x 36 x 30	B 33	2.5	23.4	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 40 x 40 x 7,5	B 33	4.85	15.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 40 x 40 x 10	B 34	4.6	16.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 40 x 40 x 20	B 34	3.5	21.4	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 40 x 40 x 25	B 34	3.1	23.7	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 45 x 45 x 10	B 34	4.7	16	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 45 x 45 x 20	B 34	4.4	17	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 50 x 50 x 10	B 35	2.7	20	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 50 x 50 x 20	B 35	2.7	27.7	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 50 x 50 x 25	B 35	2.4	31.2	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 50 x 50 x 40	B 35	6.05	13.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 50 x 50 x 50	B 35	4.05	14.32	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 98 x 98 x 30	B 36	2.4	35	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 98 x 98 x 45	B 36	3.5	42	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S D 12 x 12 x 7,5	B 37	48	2.1	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S D 18 x 12 x 7,5	B 37	9	5.4	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S D 24 x 18 x 7,5	B 37	8.5	5.85	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S D 98 x 98 x 10	B 37	4.88	10.25	therm. conductive foil/ therm. cond. adhesive	universal	universal



art. no.	page	R_{th} [K/W]	dissipation loss [W]	way of fixation	socket	suitable for processor type
ICK S R 28,5 x 6,5	B 38	17.3	3.47	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 28,5 x 10	B 38	13.9	4.32	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 28,5 x 12,5	B 38	10.3	5.83	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 28,5 x 18,5	B 39	10.1	5.94	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 32,5 x 10	B 39	11.9	5.04	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 32,5 x 20	B 39	10	6	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 32,5 x 30	B 39	8.8	6.82	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 32,5 x 40	B 39	7.6	7.89	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 32,5 x 50	B 40	6.6	9.09	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 36,5 x 20	B 40	7.2	8.33	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 40 x 10	B 40	7.1	8.45	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 40 x 20	B 40	6.05	9.92	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R A 40 x 20	B 40	7.6	7.89	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 40 x 30	B 41	6.1	9.84	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 40 x 50	B 41	4.5	13.33	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 45 x 30	B 41	6	10	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 45 x 45	B 41	4.4	13.64	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 50 x 10	B 41	6	10	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 50 x 20	B 42	7	8.57	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 50 x 30	B 42	6.1	9.84	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 50 x 45	B 42	5.1	11.76	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 54 x 20	B 42	6.1	9.84	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 54 x 30	B 42	5.05	11.88	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 54 x 45	B 43	4.1	14.63	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 70 x 30	B 43	4	15	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 70 x 50	B 43	3.5	17.14	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 85 x 30	B 43	3.7	16.22	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 85 x 45	B 43	3.4	17.65	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 98 x 30	B 44	3.7	16.22	therm. conductive foil/ therm. cond. adhesive	universal	universal

Heatsinks for IC processor

art. no.	page	R_{th} [K/W]	dissipation loss [W]	way of fixation	socket	suitable for processor type
ICK S R 98 x 50	B 44	2.95	20.34	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 100 x 50	B 44	2.3	26	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 100 x 70	B 44	2	30	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 120 x 50	B 45	1.9	31.6	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 120 x 70	B 45	1.8	33.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 140 x 50	B 45	1.85	32.4	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 140 x 70	B 45	1.7	35.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 160 x 70	B 46	1.6	37.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 23,5 x 14	B 47	18.58	6.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 23,5 x 14 G	B 47	19.16	6.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 27 x 10	B 47	17.69	6.7	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 27 x 10 G	B 47	18.24	6.6	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 28 x 15	B 47	15.24	7.8	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 28 x 15 G	B 48	15.72	7.6	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 29 x 11,5	B 48	17.26	8.2	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 29 x 11,5 G	B 48	17.8	8	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 32 x 14	B 48	15.23	7.8	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 32 x 14 G	B 48	15.23	7.6	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 33 x 10	B 48	17.6	6.8	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 33 x 10 G	B 48	18.15	6.6	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 33 x 16,5	B 49	13.87	8.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 33 x 16,5 G	B 49	14.3	8.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 35 x 10	B 49	16.9	9.35	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 35 x 10 G	B 49	17.5	9.2	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 36 x 12	B 49	12.88	10	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 36 x 12 G	B 49	13.28	8.9	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 40 x 10	B 49	12.28	9.45	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 40 x 10 G	B 50	12.66	9.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 40 x 27	B 50	9.41	12.1	therm. conductive foil/ therm. cond. adhesive	universal	universal

art. no.	page	R_{th} [K/W]	dissipation loss [W]	way of fixation	socket	suitable for processor type
ICK LED R 40 x 27 G	B 50	9.71	11.9	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 45,7 x 16,5	B 50	10.46	11.05	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 45,7 x 16,5 G	B 50	10.49	10.8	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 50 x 10	B 50	10.57	10.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 50 x 10 G	B 51	10.9	10.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 50,8 x 16,5	B 51	10.17	11.1	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 50,8 x 16,5 G	B 51	10.49	10.9	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 54 x 20	B 51	9.48	12.1	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 54 x 20 G	B 51	9.78	11.9	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 66 x 40	B 52	3.2	21	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 75 x 10	B 52	5.2	12.1	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 84 x 40	B 52	2.5	14.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 100 x 40	B 52	2	27	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 160 x 40	B 53	1.4	42	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 200 x 40	B 53	1	51	therm. conductive foil/ therm. cond. adhesive	universal	universal
SK LED 1	B 63	15				
SK LED 2	B 63	9				
SK LED 3	B 63	7				
SK LED 5	B 64	12.5				
SK LED 6	B 64	14.2				
SK LED 7	B 64	9.2				
SK LED 4	B 65	2				
ICK PPC 51	B 73	8.1	14	screw fastening		Power PC
ICK PEN 3 XE	B 73	2	31.3	screw fastening	Slot 2	Intel® Pentium® III- Xeon™ Slot II Format
ICK PEN 3 XE 1	B 73	1.8	33.6	screw fastening	Slot 2	Intel® Pentium® III- Xeon™ Slot II Format
ICK EM 22	B 73	4.4	18.1	screw fastening		MQ7 Board
ICK EM 25	B 73	3.9	20.4	screw fastening		Q7 Board
ICK PEN 38 F	B 74	4	15.1	therm. conductive foil	socket 7/ socket 370	AMD® K6-III/ IDT W2A/ MMX/ IDT C6/ Intel® Pentium®/ AMD® K6-2
ICK PEN 38 W	B 74	4	15.1	therm. cond. adhesive	socket 7/ socket 370	AMD® K6-III/ IDT W2A/ MMX/ IDT C6/ Intel® Pentium®/ AMD® K6-2

A

Heatsinks for IC processor

B

art. no.	page	R_{th} [K/W]	dissipation loss [W]	way of fixation	socket	suitable for processor type
ICK PEN 45 W	B 74	3.5	21	therm. cond. adhesive	socket 7/ socket 370	AMD® K6-III/ IDT W2A/ MMX/ IDT C6/ Intel® Pentium®/ AMD® K6-2
ICK PRO 40 W	B 74	2.7	22	therm. cond. adhesive	socket 8	Intel® Pentium® PRO
ICK PEN 3 FC	B 74	3.5	22	fixing clamp	socket 7/ socket 370	Intel® Pentium® III FC PGA (Mendocino, Cop- permire)

D

E

F

G

H

I

K

L

M

N

B 9


Fan coolers for IC processor

art. no.	page	R_{th} [K/W]	dissipation loss [W]	way of fixation	socket	suitable for processor type
LA LED 40 x 30	B 66	1.4	35	therm. conductive foil/ therm. cond. adhesive	universal	universal
LA LED 50 x 20	B 66	1.25	40	therm. conductive foil/ therm. cond. adhesive	universal	universal
LA LED 50 x 45	B 66	0.9	50	therm. conductive foil/ therm. cond. adhesive	universal	universal
LA ICK 15 x 15 F 05	B 75	2.3	22.2	therm. conductive foil	universal	universal
LA ICK 15 x 15 F 12	B 75	2.3	22.2	therm. conductive foil	universal	universal
LA ICK 17 x 17 F 12	B 75	1.6	35.8	therm. conductive foil	universal	universal
LA ICK 17 x 17 F 12 A	B 75	1.6	35.8	therm. conductive foil	universal	universal
LA ICK 17 x 17 W 05	B 75	1.6	35.8	therm. cond. adhesive	universal	universal
LA ICK 17 x 17 W 12	B 75	1.6	35.8	therm. cond. adhesive	universal	universal
LA ICK 18 x 18 F 12	B 75	1.5	41.7	therm. conductive foil	universal	universal
LA ICK 18 x 18 W 12	B 75	1.5	41.7	therm. cond. adhesive	universal	universal
LA ICK 21 x 21 F 05	B 75	1.4	46.3	therm. conductive foil	universal	universal
LA ICK 21 x 21 F 12	B 75	1.4	46.3	therm. conductive foil	universal	universal
LA ICK 21 x 21 W 05	B 75	1.4	46.3	therm. cond. adhesive	universal	universal
LA ICK 21 x 21 W 12	B 75	1.4	46.3	therm. cond. adhesive	universal	universal
LA ICK PEN 8 F 05	B 76	2.5	23.4	therm. conductive foil	socket 7/ socket 370	AMD® K6-III/ IDT W2A/ Cyrix MII and similar/ MMX/ IDT C6/ Intel® Pentium®/ AMD® K6-2
LA ICK PEN 8 F 12	B 76	2.5	23.4	therm. conductive foil	socket 7/ socket 370	AMD® K6-III/ IDT W2A/ Cyrix MII and similar/ MMX/ IDT C6/ Intel® Pentium®/ AMD® K6-2
LA ICK PEN 8 W 05	B 76	2.5	23.4	therm. cond. adhesive	socket 7/ socket 370	AMD® K6-III/ IDT W2A/ Cyrix MII and similar/ MMX/ IDT C6/ Intel® Pentium®/ AMD® K6-2
LA ICK PEN 8 W 12	B 76	2.5	23.4	therm. cond. adhesive	socket 7/ socket 370	AMD® K6-III/ IDT W2A/ Cyrix MII and similar/ MMX/ IDT C6/ Intel® Pentium®/ AMD® K6-2
LA ICK PEN 16 W 12	B 76	1.2	51.1	therm. cond. adhesive	socket 7/ socket 370	AMD® K6-III/ IDT W2A/ Cyrix MII and similar/ MMX/ IDT C6/ Intel® Pentium®/ AMD® K6-2

A

Fan coolers for IC processor

B

C

D

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F

G

H

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K

L

M

art. no.	page	R_{th} [K/W]	dissipation loss [W]	way of fixation	socket	suitable for processor type
LA ICK PEN 16 W 12 A	B 76	1.2	51.1	therm. cond. adhesive	socket 7/ socket 370	AMD® K6-III/ IDT W2A/ Cyrix MII and similar/ MMX/ IDT C6/ Intel® Pentium®/ AMD® K6-2
LA ICK PEN 18 W 12	B 76	1.6	38.6	therm. cond. adhesive	socket 7/ socket 370	AMD® K6-III/ IDT W2A/ Cyrix MII and similar/ MMX/ IDT C6/ Intel® Pentium®/ AMD® K6-2
LA ICK PEN 38 W 12	B 76	1.1	53.6	therm. cond. adhesive	socket 7/ socket 370	AMD® K6-III/ IDT W2A/ Cyrix MII and similar/ MMX/ IDT C6/ Intel® Pentium®/ AMD® K6-2
LA ICK PRO 25 F 12	B 76	0.97	60	therm. conductive foil	socket 8	Intel® Pentium® PRO
LA ICK PEN 2 K 12	B 77	1.2	58		Slot A/ Slot 1	Intel® Pentium® II/ AMD® Athlon®
LA ICK PEN 3 XE	B 77	0.8	61.8	screw fastening	Slot 2	Intel® Pentium® III- Xeon™
LA ICK PEN 4 1 K	B 77	0.6	85	fixing clamp	socket 463/ socket 423	Intel® Pentium® IV

N

B 11
EL.ITALIA

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Fan coolers for IC processor

Heatsinks

- excellent thermal efficiency achieved by flow-favourable omnidirectional fin geometry and black anodised surface
- easy mounting using fixing clamp, thermally conductive adhesive foil or thermally conductive glue

B

Fan coolers

- special high-grade industrial type
- compact design with high mechanical stability
- fan motor axle with double ball bearings ensures high reliability and long product life
- low current consumption and thus low self-heating
- effective heat dissipation achieved by optimum design of fan motor and heatsink
- fan motors with other operating voltages on request
- fan motors also available with pulse output and alarm device circuit

C

Technical introduction

- the thermal resistances and the power dissipation were determined with an ambient temperature of 25 °C and an IC case-temperature of 85 °C
- with higher IC case-temperature, the power to be dissipated increases proportionally

D

Fixing methods

K = fixing clamp

F = double sided thermally conductive adhesive foil

W = thermally conductive glue

SB = screw fixing

E

F

Technical data for fans with pulse output → B 78

- pulse output for control of the alarm device circuit
- puls form is like rectangle with the triple frequency of rotation speed
- with blocked rotor the output signal can be L (0.8 V) or H (V_{cc}-1V)
- the pulse output must not be connected with GND or V_{cc} without a multiplier (>10K)
- to prevent short circuits, do not isolate the used puls output

G

H

I

K

L

M



N